



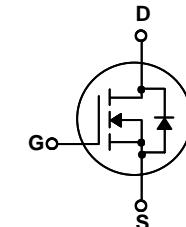
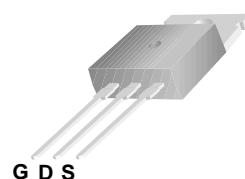
Technology Int'l

WFP2N60

600V N-Channel MOSFET

Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 8.5\text{nC}$ (Typ.)
- $\text{BVDSS}=600\text{V}, \text{ID}=2\text{A}$
- $R_{DS(on)} : 5 \Omega$ (Max) @ $\text{VG}=10\text{V}$
- 100% Avalanche Tested



TO-220

G-Gate,D-Drain,S-Source

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	WFP2N60	Units
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current -continuous ($T_c=25^\circ\text{C}$)	2	A
	-continuous ($T_c=100^\circ\text{C}$)	1.5	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Plused Avalanche Energy (Note1)	120	mJ
I_{AR}	Avalanche Current (Note2)	2	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	54	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 ~ +150	$^\circ\text{C}$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	--	1.95	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance,Case to Sink	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	--	62.5	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{ID}=250 \mu\text{A}, \text{VGS}=0$	600	--	--	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$\text{I}_D=250 \mu\text{A}$, Reference to 25°C	--	0.4	--	V/ $^\circ\text{C}$
IDSS	Zero Gate Voltage Drain Current	$\text{Vds}=600\text{V}, \text{Vgs}=0\text{V}$	--	--	1	μA
		$\text{Vds}=480\text{V}, \text{Tc}=125^\circ\text{C}$			10	μA
IGSSF	Gate-body leakage Current, Forward	$\text{Vgs}=+30\text{V}, \text{Vds}=0\text{V}$	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	$\text{Vgs}=-30\text{V}, \text{Vds}=0\text{V}$	--	--	-100	nA

On Characteristics

$\text{V}_{\text{GS(th)}}$	Date Threshold Voltage	$\text{Id}=250\mu\text{A}, \text{Vds}=\text{Vgs}$	2	--	4	V
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$\text{Id}=1\text{A}, \text{Vgs}=10\text{V}$	--	--	5	Ω

Dynamic Characteristics

Ciss	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	270	350	pF
Coss	Output Capacitance		--	40	50	pF
Crss	Reverse Transfer Capacitance		--	5	7	pF

Switching Characteristics

Td(on)	Turn-On Delay Time	VDD=300V, ID=2A RG=25 Ω (Note 3,4)	--	10	30	nS
Tr	Turn-On Rise Time		--	25	60	nS
Td(off)	Turn-Off Delay Time		--	20	50	nS
Tf	Turn-Off Fall Time		--	25	60	nS
Qg	Total Gate Charge	VDS=480,VGS=10V, ID=2A (Note 3,4)	--	90	11	nC
Qgs	Gate-Source Charge		--	1.6	--	nC
Qgd	Gate-Drain Charge		--	4.3	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	2	A	
I_{SM}	Maximum Plused Drain-Source DiodeForward Current	--	--	8	A	
V_{SD}	Drain-Source Diode Forward Voltage	$\text{Id}=2\text{A}$	--	--	1.5	V
trr	Reverse Recovery Time	$\text{I}_S=2\text{A}, \text{V}_{\text{GS}}=0\text{V}$	--	180	--	nS
Qrr	Reverse Recovery Charge	$\text{di}_F/\text{dt}=100\text{A}/\mu\text{s}$ (Note3)	--	0.72	--	μC

*Notes 1, L=55mH, IAS=2.0A, VDD=50V, RG=25 Ω , Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

4, Essentially Independent of Operating Temperature

Typical Characteristics

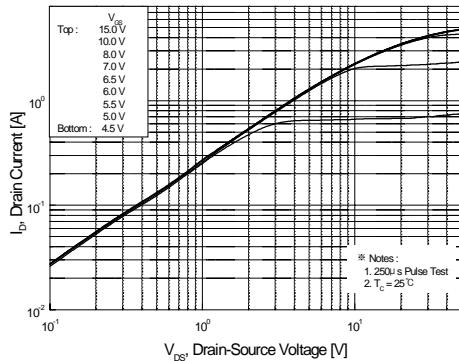


Figure 1. On-Region Characteristics

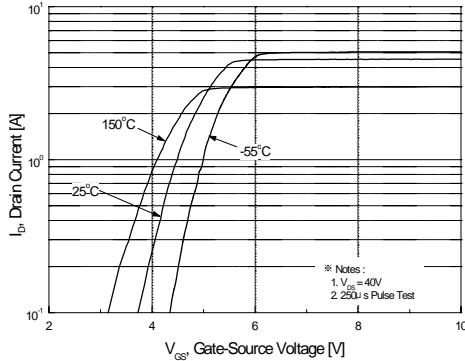


Figure 2. Transfer Characteristics

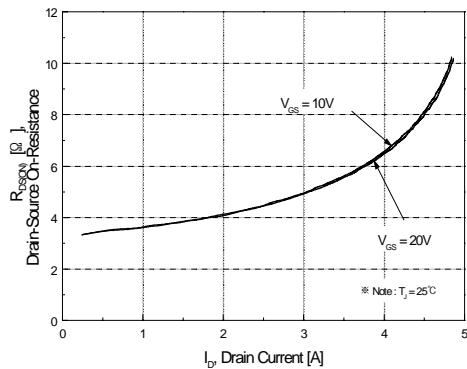


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

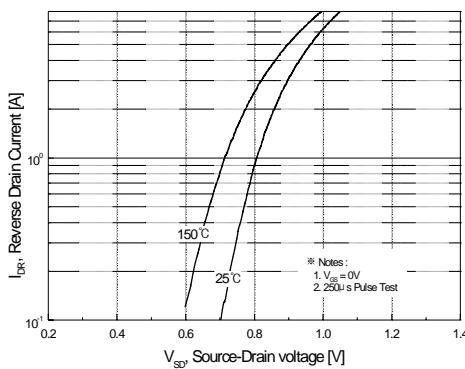


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

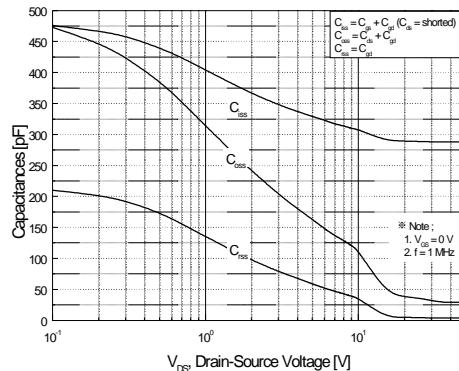


Figure 5. Capacitance Characteristics

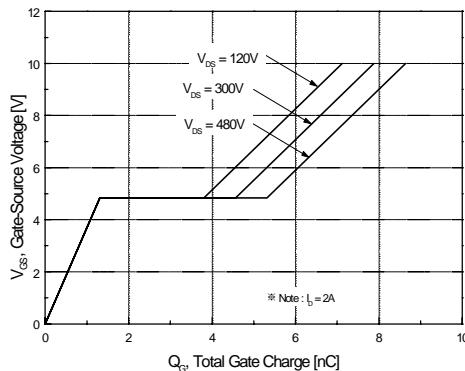
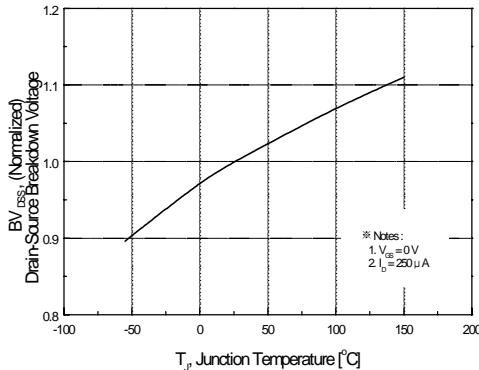
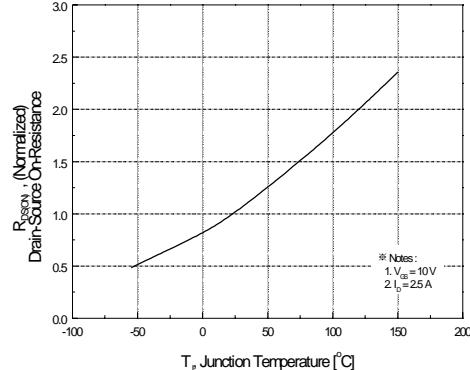


Figure 6. Gate Charge Characteristics

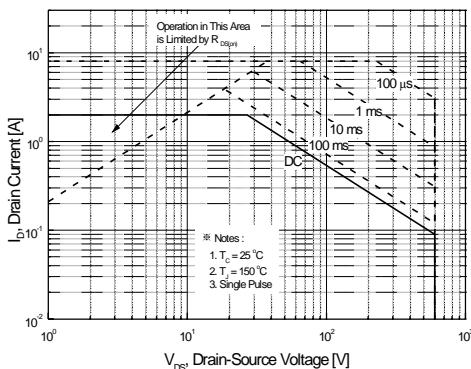
Typical Characteristics (Continued)



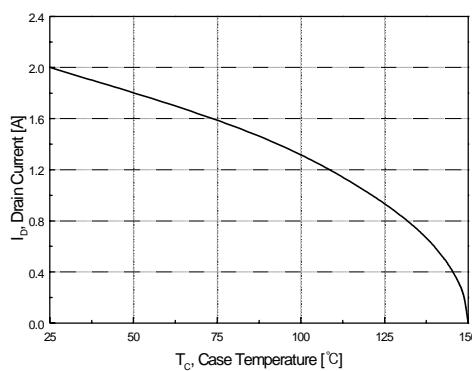
**Figure 7. Breakdown Voltage Variation
vs Temperature**



**Figure 8. On-Resistance Variation
vs Temperature**



**Figure 9-1. Maximum Safe Operating Area
for WFP2N60**



**Figure 10. Maximum Drain Current
vs Case Temperature**

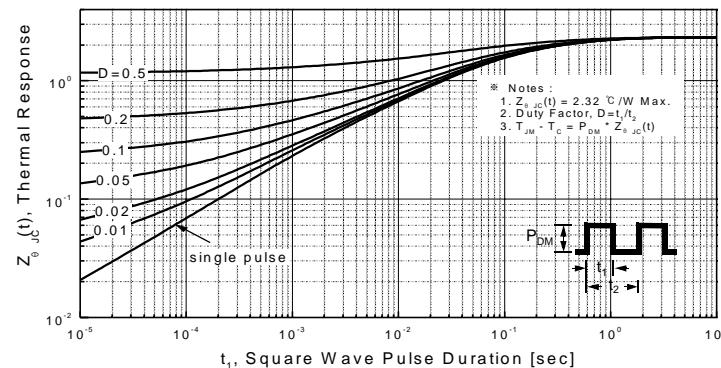
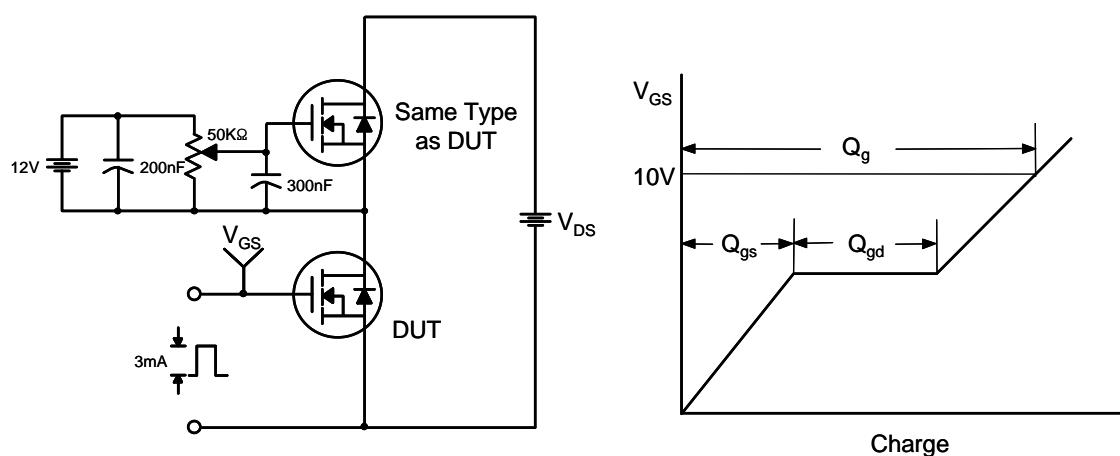
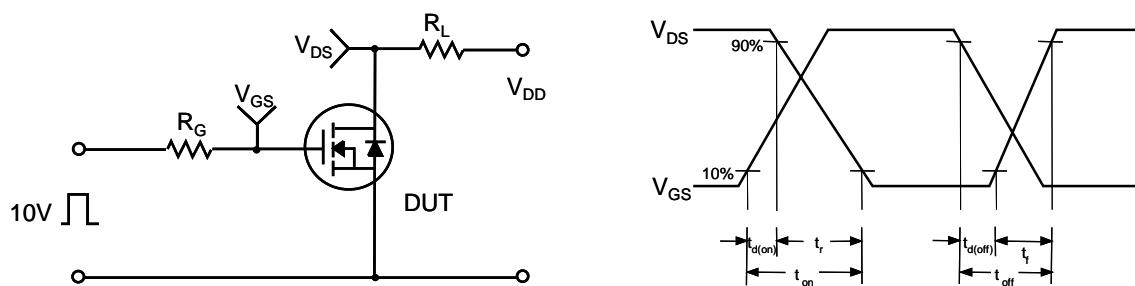


Figure 11-1. Transient Thermal Response Curve for WFP2N60

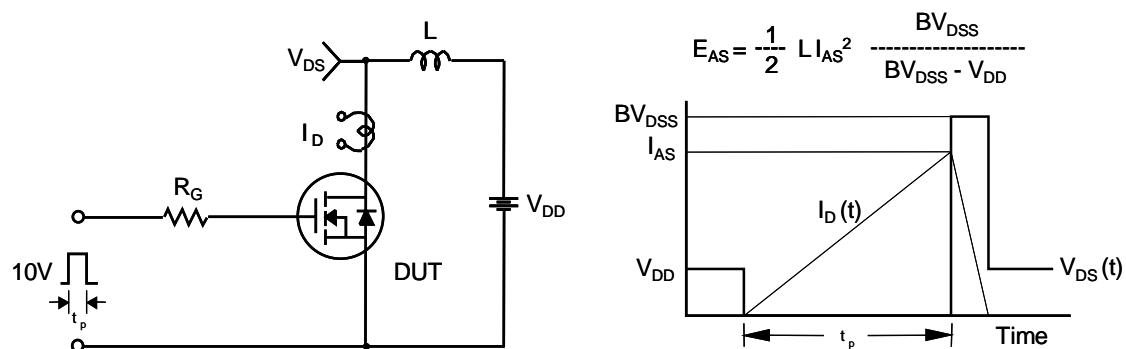
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

